**Product data sheet** 

## 1. General description

Silicon Carbide Schottky diode in a TO247-2L plastic package, designed for high frequency switched-mode power supplies.



### 2. Features and benefits

- New 6th Generation Technology
- Low Forward Voltage Drop
- Low Reverse Leakage Current
- High Forward Surge Capability I<sub>FSM</sub>
- Reduced losses in associated MOSFET
- Reduced EMI
- · Reduced cooling requirements
- RoHS compliant
- · AEC-Q101 qualified

# 3. Applications

- Power factor correction
- Telecom / Server SMPS
- UPS
- PV inverter
- PC Silverbox
- LED / OLED TV
- Motor Drives
- · On board charger

### 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	S Values			Unit
Absolute	maximum rating						
$V_{RRM}$	repetitive peak reverse voltage				650		V
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; square-wave pulse; $T_{mb} \le$ 127 °C; Fig. 1; Fig. 2; Fig. 3		20 A		А	
T <sub>j</sub>	junction temperature			-55 to 175		°C	
Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
Static ch	aracteristics						
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 20 A; T <sub>j</sub> = 25 °C; <u>Fig. 5</u>		-	1.26	1.40	V
		I <sub>F</sub> = 20 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>		-	1.35	1.55	V
Dynamic	characteristics				1	,	
Q <sub>r</sub>	recovered charge	$I_F = 20 \text{ A}; dI_F/dt = 500 \text{ A/}\mu\text{s}; V_R = 400 \text{ V};$ $T_i = 25 ^{\circ}\text{C}; Fig. 7$		-	48	-	nC

# 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	К	cathode		K — A
2	А	anode		001aaa020
mb	mb	mounting base; connected to cathode	K A TO247-2L	

# 6. Ordering information

### **Table 3. Ordering information**

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
WNSC6D20650W-A	TO247-2L	WNSC6D20650W-A6Q	Tube	30	TO247L-2L	10-Nov-2020

# 7. Marking

#### Table 4. Marking codes

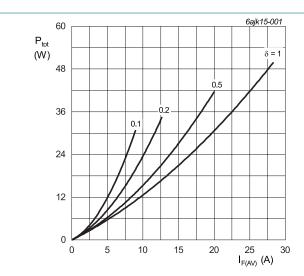
Type number	Marking codes
WNSC6D20650W-A	WNSC6D 20650W-A

# 8. Limiting values

#### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage			650	V
$V_{\text{RWM}}$	crest working reverse voltage			650	V
$V_R$	reverse voltage	DC		650	V
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; square-wave pulse; $T_{mb} \le$ 127 °C; Fig. 1; Fig. 2; Fig. 3		20	А
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5; t <sub>p</sub> = 25 μs; T <sub>mb</sub> ≤ 127 °C; square-wave pulse		40	А
I <sub>FSM</sub>	non-repetitive peak	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		140	Α
	forward current	$t_p = 10 \mu s; T_{j(init)} = 25 °C; square-wave pulse$		1000	Α
l²t	I <sup>2</sup> t for fusing	sine-wave pulse; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 10 \text{ ms}$		98	A <sup>2</sup> s
T <sub>stg</sub>	storage temperature			-55 to 175	°C
T <sub>j</sub>	junction temperature			-55 to 175	°C



 $I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$  $V_o = 0.984 \text{ V}; R_s = 0.0274 \Omega$ 

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

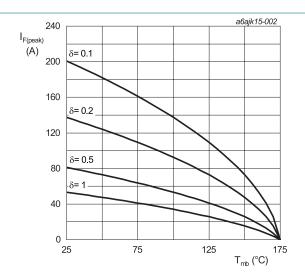
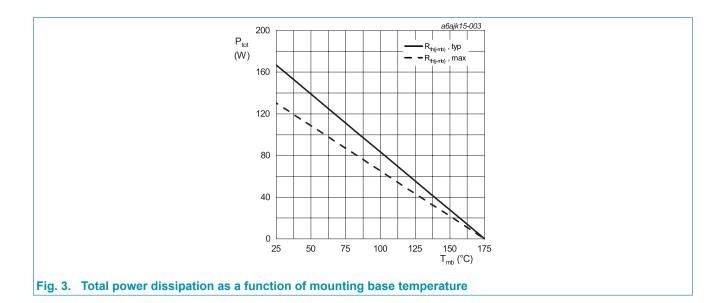


Fig. 2. Current derating as a function of mounting base temperature



### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Notes	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 4		-	0.9	1.15	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient	in free air		-	60	-	K/W

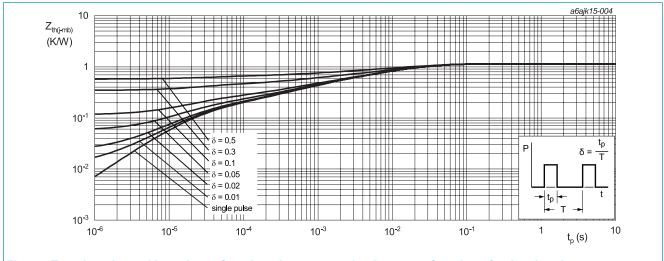
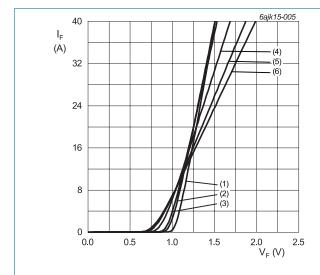


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

### 10. Characteristics

**Table 7. Characteristics** 

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Symbol	ol Parameter Conditions		Notes	Min	Тур	Max	Unit
Static cha	aracteristics						
$V_{F}$	forward current	$I_F = 20 \text{ A}; T_j = 25 \text{ °C}; Fig. 5$		-	1.26	1.40	V
		I <sub>F</sub> = 20 A; T <sub>j</sub> = 150 °C; <u>Fig. 5</u>		-	1.35	1.55	V
		I <sub>F</sub> = 20 A; T <sub>j</sub> = 175 °C; <u>Fig. 5</u>		-	1.40	1.60	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 650 V; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>		-	2	100	μΑ
		V <sub>R</sub> = 650 V; T <sub>j</sub> = 175 °C; <u>Fig. 6</u>		-	30	400	μΑ
Dynamic	characteristics						
$Q_r$	recovered charge	$I_F = 20 \text{ A}$ ; $V_R = 400 \text{ V}$ ; $dI_F/dt = 500 \text{ A/}\mu\text{s}$ ; $T_j = 25 ^{\circ}\text{C}$ ; Fig. 7		-	48	-	nC
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; T <sub>j</sub> = 25 °C		-	1005	-	pF
		f = 1 MHz; V <sub>R</sub> = 300 V; T <sub>j</sub> = 25 °C		-	110	-	pF
		f = 1 MHz; V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C		-	102	-	pF
E <sub>as</sub>	non-repetitive avalanche energy	I <sub>R</sub> = 7.8 A; L = 5 mH; T <sub>j(init)</sub> = 25 °C		150	-	-	mJ



 $V_o$  = 0.984 V;  $R_s$  = 0.0274  $\Omega$ 

(1)  $T_j = -55$  °C; typical values

(2)  $T_j = 0$  °C; typical values

(3) T<sub>i</sub> = 25 °C; typical values

(4) T<sub>i</sub> = 100 °C; typical values

(5)  $T_j = 150 \,^{\circ}\text{C}$ ; typical values

(6) T<sub>i</sub> = 175 °C; typical values

Fig. 5. Forward current as a function of forward voltage; typical values

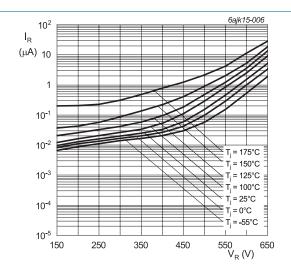


Fig. 6. Reverse leakage current as a function of reverse voltage; typical value

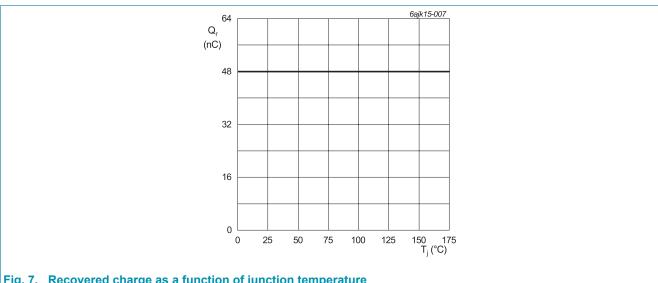
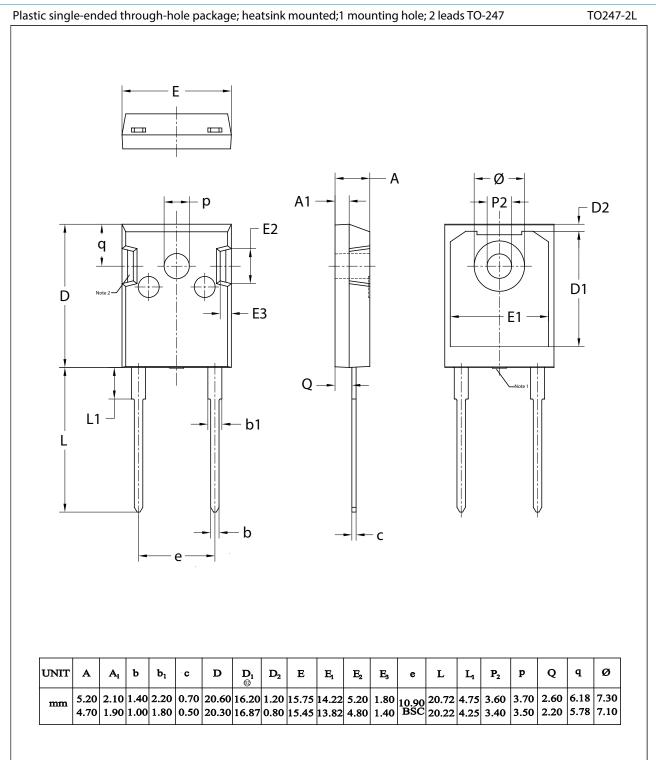


Fig. 7. Recovered charge as a function of junction temperature

# 11. Package outline



### Note:

- Mold resin protrusion max 0.127mm.
- Metal exposed with Sn plating.

### 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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